

SEMICONDUCTOR PACKAGE WITH HEAT SINK

ABSTRACT

A semiconductor package with a heat sink is provided. At least one chip and a heat sink attached to the chip are mounted on a substrate. At least one slot is formed through at least one corner of the heat sink at a position attached to the substrate. An adhesive material is applied between the heat sink and substrate and over filled in the slot with an overflow of the adhesive material out of the slot. The adhesive material over filled in the slot provides an anchoring effect and increases its contact area with the heat sink to thereby firmly secure the heat sink on the substrate. Further, the slot formed at the corner of the heat sink can alleviate thermal stresses accumulated at the corner of the heat sink and thereby prevent delamination between the heat sink and the substrate.

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